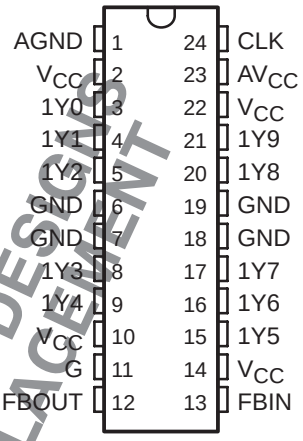
- **Use *CDCVF2510A* as a Replacement for this Device**
- **Spread Spectrum Clock Compatible**
- **100-MHz Maximum Frequency**
- **Available in Plastic 24-Pin TSSOP**
- **Phase-Lock Loop Clock Distribution for Synchronous DRAM Applications**
- **Distributes One Clock Input to One Bank of Ten Outputs**
- **Single Output Enable Terminal Controls All Ten Outputs**
- **External Feedback (FBIN) Pin Is Used to Synchronize the Outputs to the Clock Input**
- **On-Chip Series Damping Resistors**
- **No External RC Network Required**
- **Operates at 3.3-V V_{CC}**

PW PACKAGE
(TOP VIEW)



description

The CDC2510A is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock driver. It uses a PLL to precisely align, in both frequency and phase, the feedback (FBOUT) output to the clock (CLK) input signal. It is specifically designed for use with synchronous DRAMs. The CDC2510A operates at 3.3-V V_{CC} and provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of ten outputs provides ten low-skew, low-jitter copies of CLK. Output signal duty cycles are adjusted to 50 percent, independent of the duty cycle at CLK. All outputs can be enabled or disabled via a single output enable input. When the G input is high, the outputs switch in phase and frequency with CLK; when the G input is low, the outputs are disabled to the logic-low state.

Unlike many products containing PLLs, the CDC2510A does not require external RC networks. The loop filter for the PLL is included on-chip, minimizing component count, board space, and cost.

Because it is based on PLL circuitry, the CDC2510A requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization time is required, following power up and application of a fixed-frequency, fixed-phase signal at CLK, and following any changes to the PLL reference or feedback signals. The PLL can be bypassed for test purposes by strapping AV_{CC} to ground.

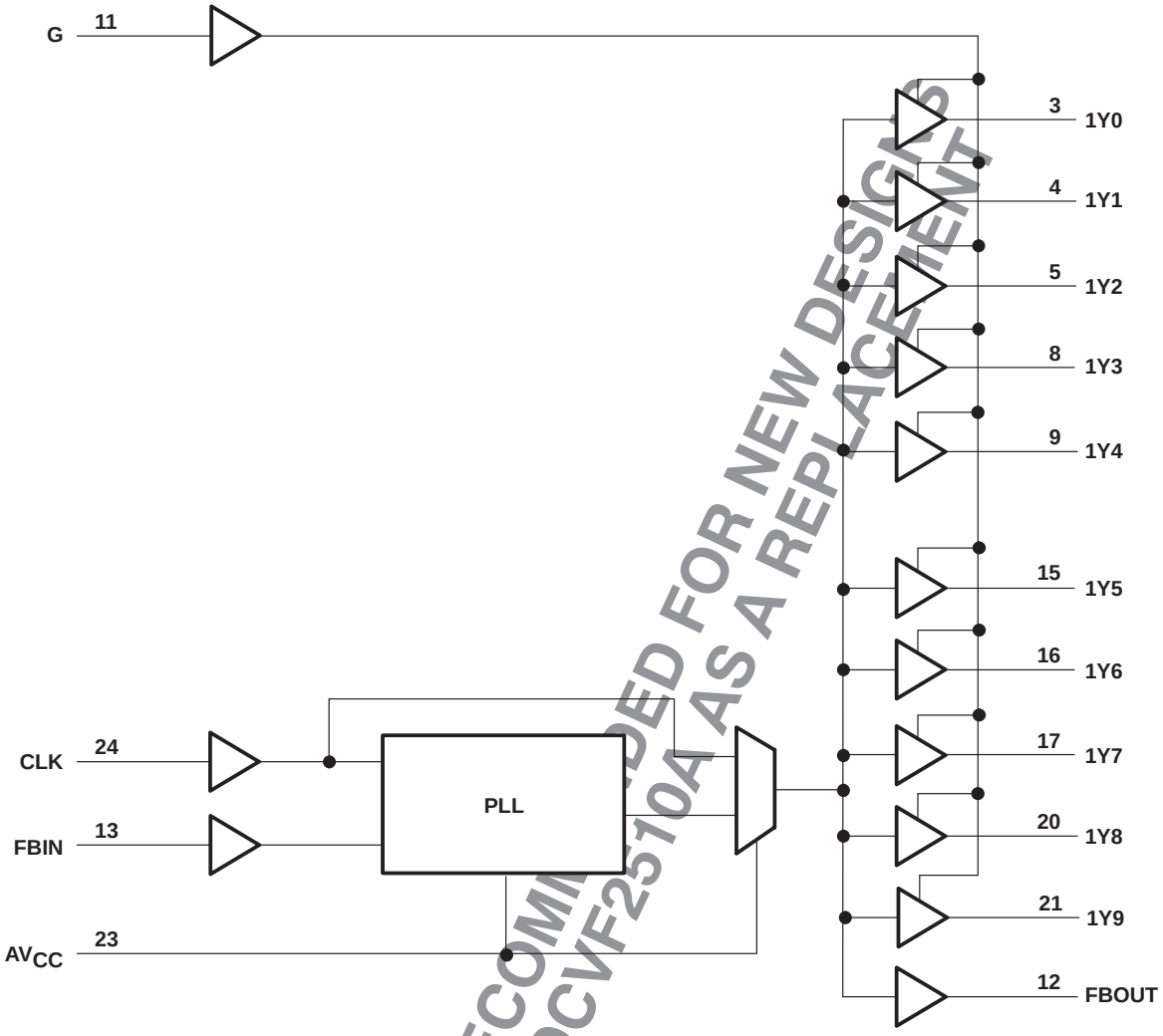
The CDC2510A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OUTPUTS	
G	CLK	1Y (0:9)	FBOUT
X	L	L	L
L	H	L	H
H	H	H	H

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

functional block diagram



AVAILABLE OPTIONS

T_A	PACKAGE
	SMALL OUTLINE (PW)
0°C to 70°C	CDC2510A

Terminal Functions

TERMINAL		TYPE	DESCRIPTION
NAME	NO.		
CLK	24	I	Clock input. CLK provides the clock signal to be distributed by the CDC2510A clock driver. CLK is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLK must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid CLK signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to its reference signal.
FBIN	13	I	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be hard-wired to FBOUT to complete the PLL. The integrated PLL synchronizes CLK and FBIN so that there is nominally zero phase error between CLK and FBIN.
G	11	I	Output bank enable. G is the output enable for outputs 1Y(0:9). When G is low, outputs 1Y(0:9) are disabled to a logic-low state. When G is high, all outputs 1Y(0:9) are enabled and switch at the same frequency as CLK.
FBOUT	12	O	Feedback output. FBOUT is dedicated for external feedback. It switches at the same frequency as CLK. When externally wired to FBIN, FBOUT completes the feedback loop of the PLL. FBOUT has and integrated 25-Ω series-damping resistor.
1Y (0:9)	3, 4, 5, 8, 9 15, 16, 17, 20, 21	O	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 1Y(0:9) is enabled via the G input. These outputs can be disabled to a logic-low state by deasserting the G control input. Each output has an integrated 25-Ω series-damping resistor.
AV_{CC}	23	Power	Analog power supply. AV_{CC} provides the power reference for the analog circuitry. In addition, AV_{CC} can be used to bypass the PLL for test purposes. When AV_{CC} is strapped to ground, PLL is bypassed and CLK is buffered directly to the device outputs.
AGND	1	Ground	Analog ground. AGND provides the ground reference for the analog circuitry.
V_{CC}	2, 10, 14, 22	Power	Power supply
GND	6, 7, 18, 19	Ground	Ground

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, AV_{CC} (see Note 1) . . . . . $AV_{CC} < V_{CC}$ +0.7 V
Supply voltage range, V_{CC}, AV_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (see Note 2) . . . . . −0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V_O (see Notes 2 and 3) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$) . . . . . −50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . . ±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . . ±50 mA
Continuous current through each V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at $T_A = 55°C$ (in still air) (see Note 4) . . . . . 0.7 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. AV_{CC} **must not** exceed V_{CC}.
2. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3. This value is limited to 4.6 V maximum.
4. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 5)

	MIN	MAX	UNIT
Supply voltage, V_{CC}, AV_{CC}	3	3.6	V
High-level input voltage, V_{IH}	2		V
Low-level input voltage, V_{IL}		0.8	V
Input voltage, V_I	0	V_{CC}	V
High-level output current, I_{OH}		−12	mA
Low-level output current, I_{OL}		12	mA
Operating free-air temperature, T_A	0	70	°C

NOTE 5: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		AV_{CC}, V_{CC}	MIN	TYP‡	MAX	UNIT
V_{IK}	I_I = −18 mA		3 V			−1.2	V
V_{OH}	I_{OH} = −100 µA		MIN to MAX	V_{CC} −0.2			V
	I_{OH} = −12 mA		3 V	2.1			
	I_{OH} = −6 mA		3 V	2.4			
V_{OL}	I_{OL} = 100 µA		MIN to MAX			0.2	V
	I_{OL} = 12 mA		3 V			0.8	
	I_{OL} = 6 mA		3 V			0.55	
I_I	$V_I = V_{CC}$ or GND		3.6 V			±5	µA
I_{CC}§	$V_I = V_{CC}$ or GND,	I_O = 0, Outputs: low or high	3.6 V			10	µA
ΔI_{CC}	One input at V_{CC} − 0.6 V,	Other inputs at V_{CC} or GND	3.3 V to 3.6 V			500	µA
C_i	$V_I = V_{CC}$ or GND		3.3 V		4		pF
C_o	$V_O = V_{CC}$ or GND		3.3 V		6		pF

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
§ For I_{CC} of AV_{CC}, see Figure 5.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
f_{clk}	Clock frequency	80	100	MHz
	Input clock duty cycle	40%	60%	
	Stabilization time†		1	ms

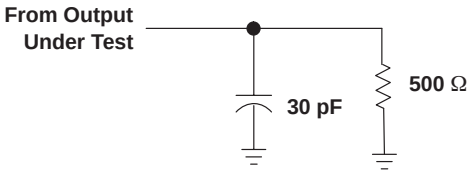
† Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 30 pF (see Note 6 and Figures 1 and 2)‡

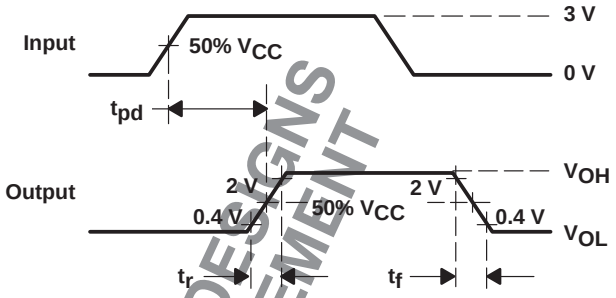
PARAMETER	FROM (INPUT)/CONDITION	TO (OUTPUT)	V_{CC}, AV_{CC} = 3.3 V ± 0.165 V			V_{CC}, AV_{CC} = 3.3 V ± 0.3 V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$t_{phase\ error}$, reference (see Note 7, Figure 3)	80 MHz < CLKIN↑ ≤ 100 MHz	FBIN↑				−700		−300	ps
$t_{phase\ error}$– jitter (see Note 8)	CLKIN↑ = 100 MHz	FBIN↑	−750		−350		−540		ps
$t_{sk(o)}$§	Any Y or FBOUT	Any Y or FBOUT						200	ps
$Jitter_{(pk\text{-}pk)}$ (see Figure 4)	Clkin = 100 MHz	Any Y or FBOUT				−150		150	ps
Duty cycle reference (see Figure 4)	F(clkin > 80 MHz)	Any Y or FBOUT				45%		55%	
t_r		Any Y or FBOUT		1.3	1.9	0.8		2.1	ns
t_f		Any Y or FBOUT		1.7	2.5	1.2		2.7	ns

‡ These parameters are not production tested.
§ The $t_{sk(o)}$ specification is only valid for equal loading of all outputs.
NOTES: 6. The specifications for parameters in this table are applicable only after any appropriate stabilization time has elapsed.
7. This is considered as static phase error.
8. Phase error does not include jitter. The total phase error is −900 ps to −200 ps for the 5% V_{CC} range.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 100 MHz, Z_O = 50 Ω, t_r ≤ 1.2 ns, t_f ≤ 1.2 ns.
C. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

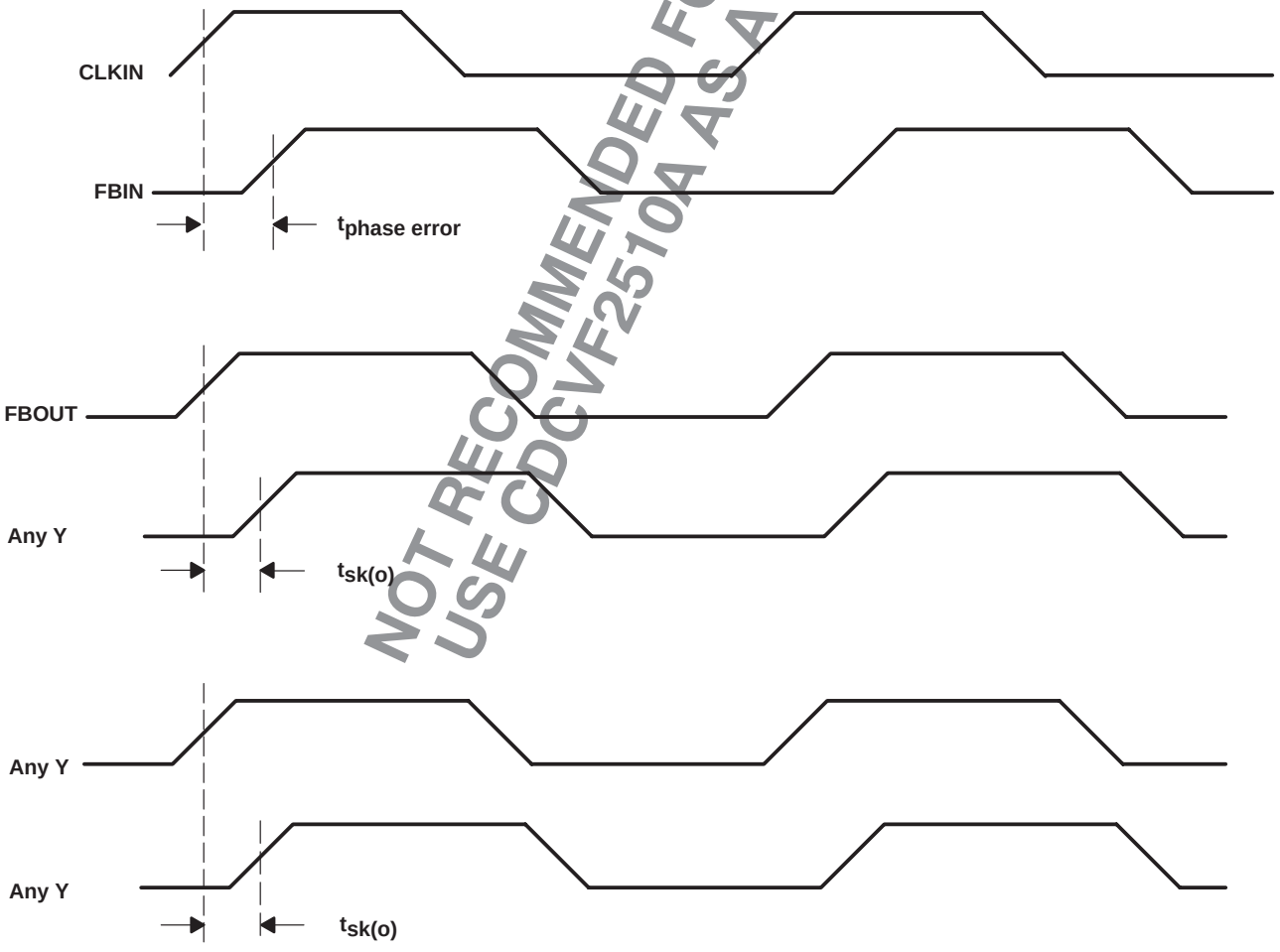


Figure 2. Phase Error and Skew Calculations

TYPICAL CHARACTERISTICS

STATIC PHASE ERROR vs CLOCK FREQUENCY

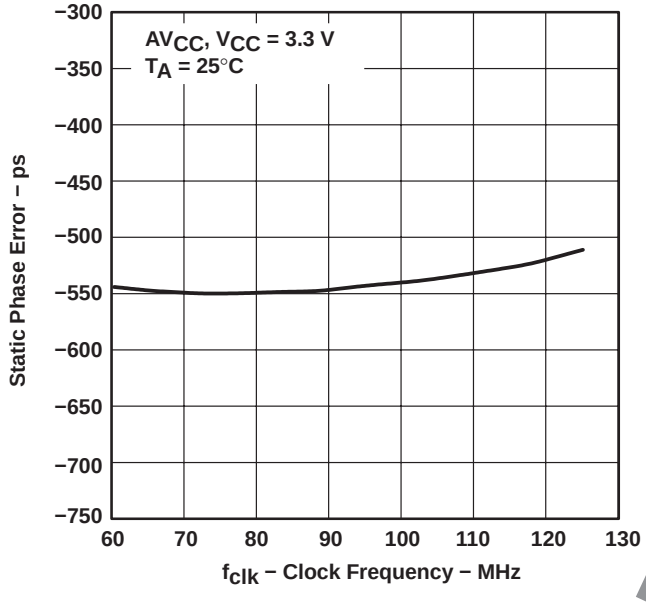


Figure 3

JITTER (PEAK-TO-PEAK) vs CLOCK FREQUENCY

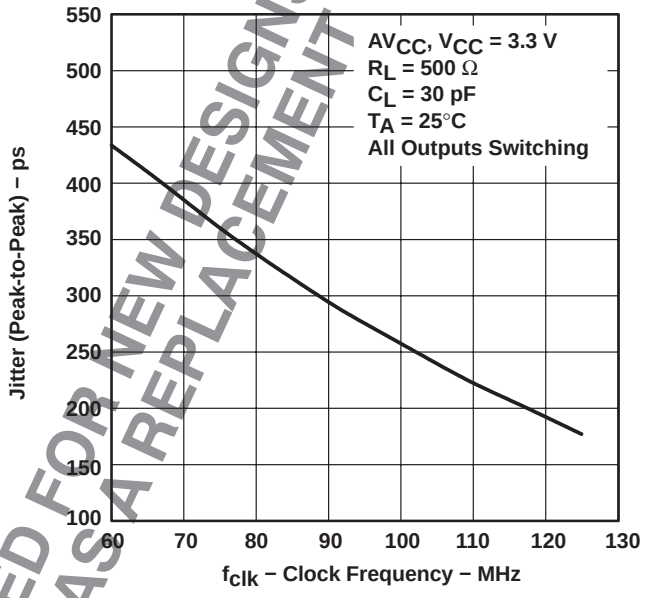


Figure 4

ANALOG SUPPLY CURRENT vs CLOCK FREQUENCY

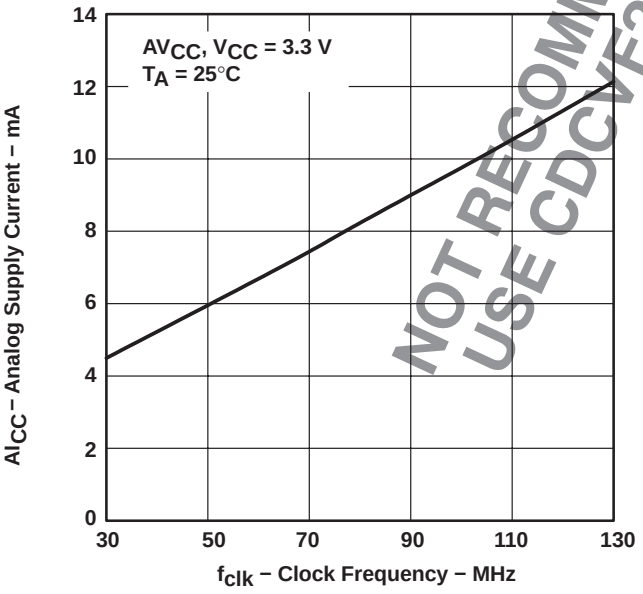


Figure 5

SUPPLY CURRENT vs CLOCK FREQUENCY

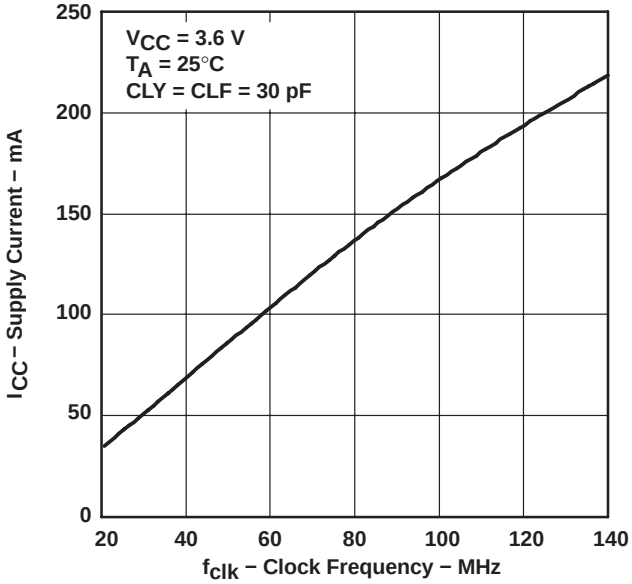
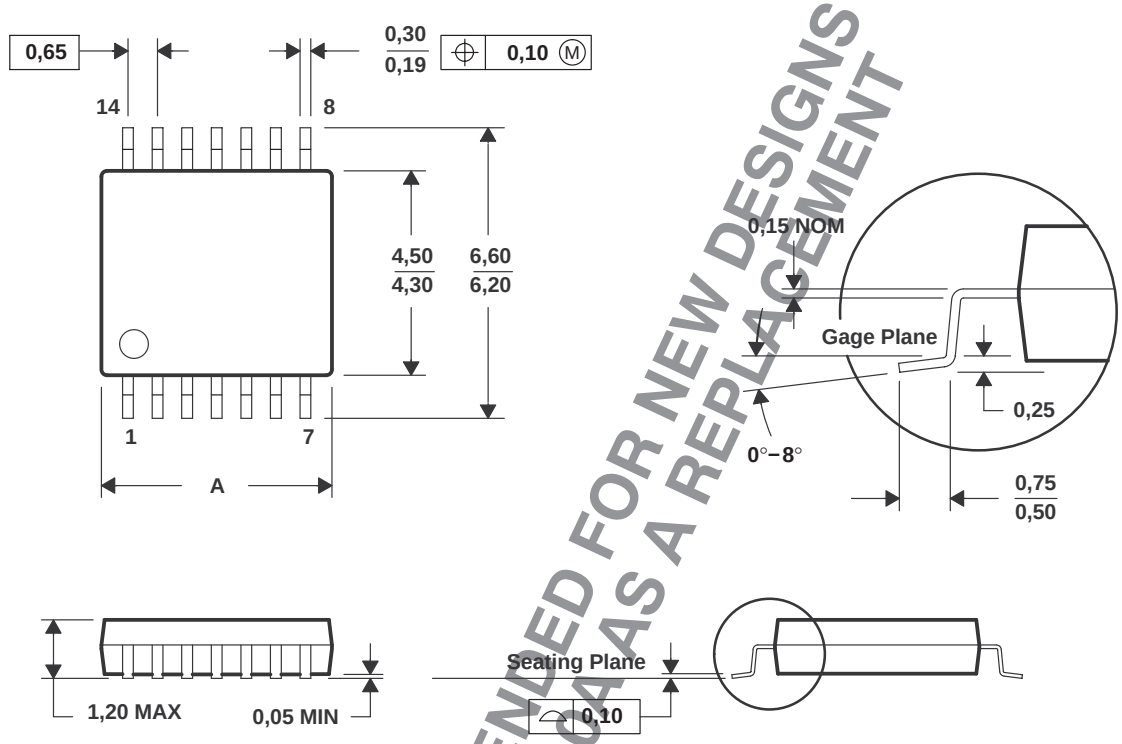


Figure 6

MECHANICAL INFORMATION

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/E 08/96

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDC2510APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC2510APWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

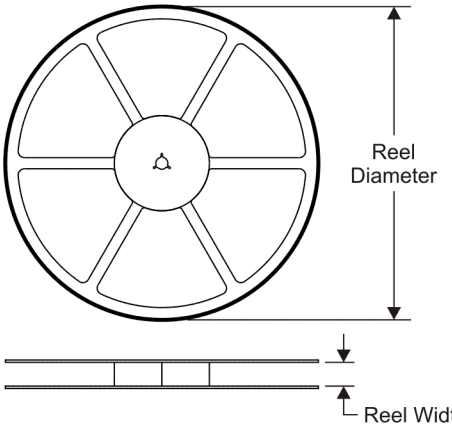
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

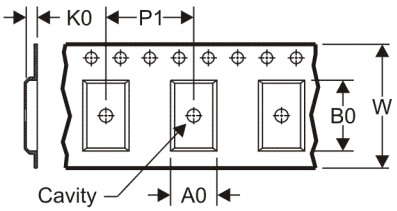
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

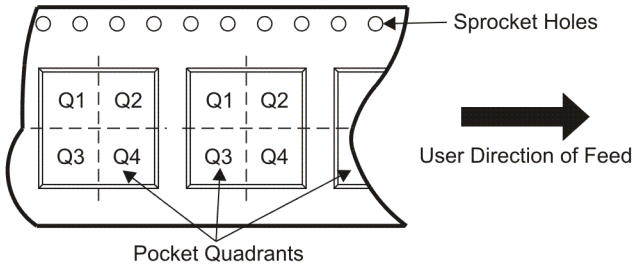


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

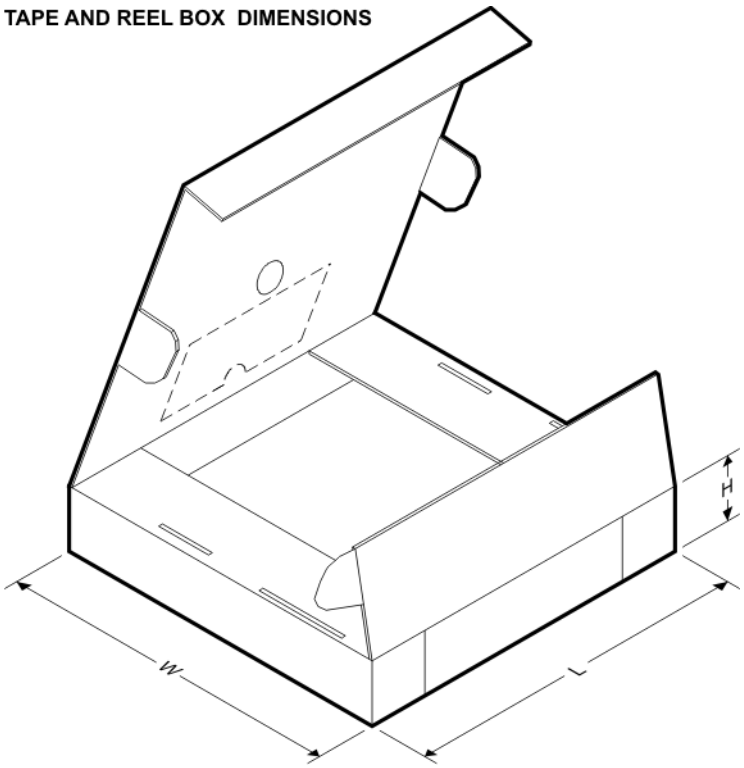
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2510APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

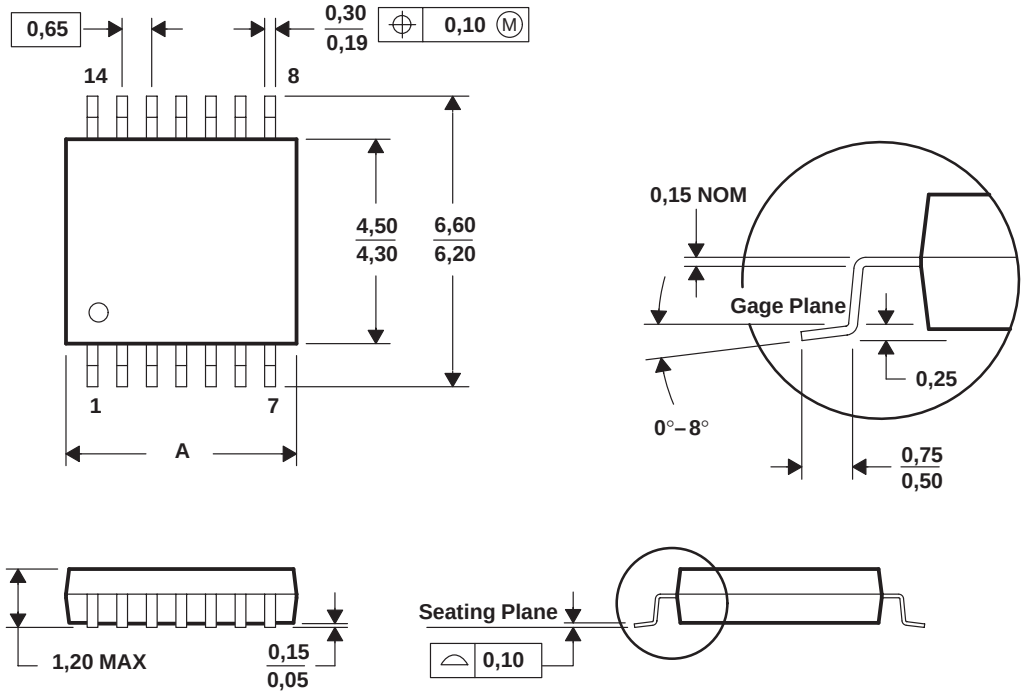


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2510APWR	TSSOP	PW	24	2000	346.0	346.0	33.0

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Logic	logic.ti.com	Military	www.ti.com/military
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Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265